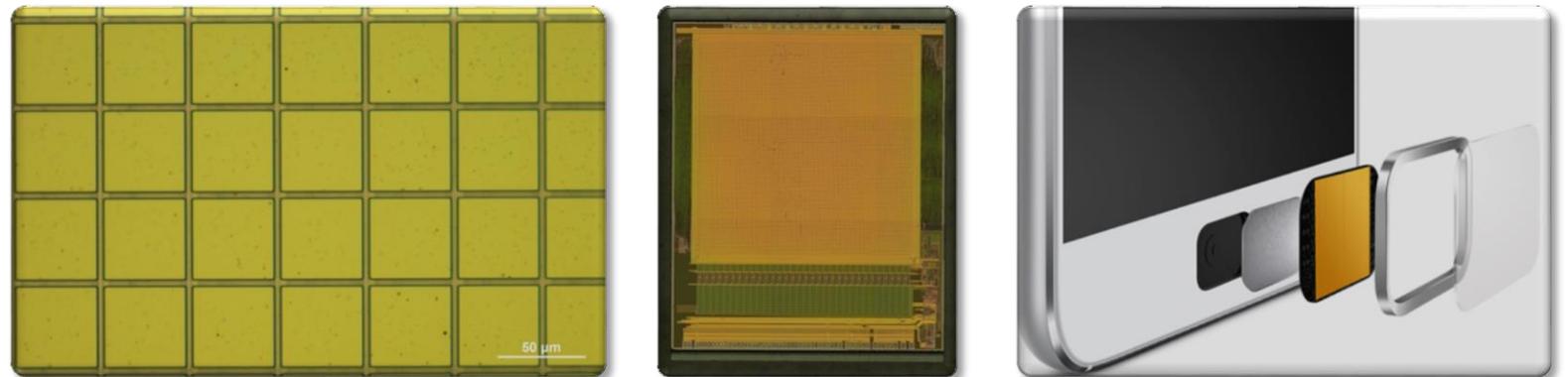


Goodix GF919

Fingerprint Sensor on Meizu MX4 Pro Phone



Product Analysis Report

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